XCede® HD
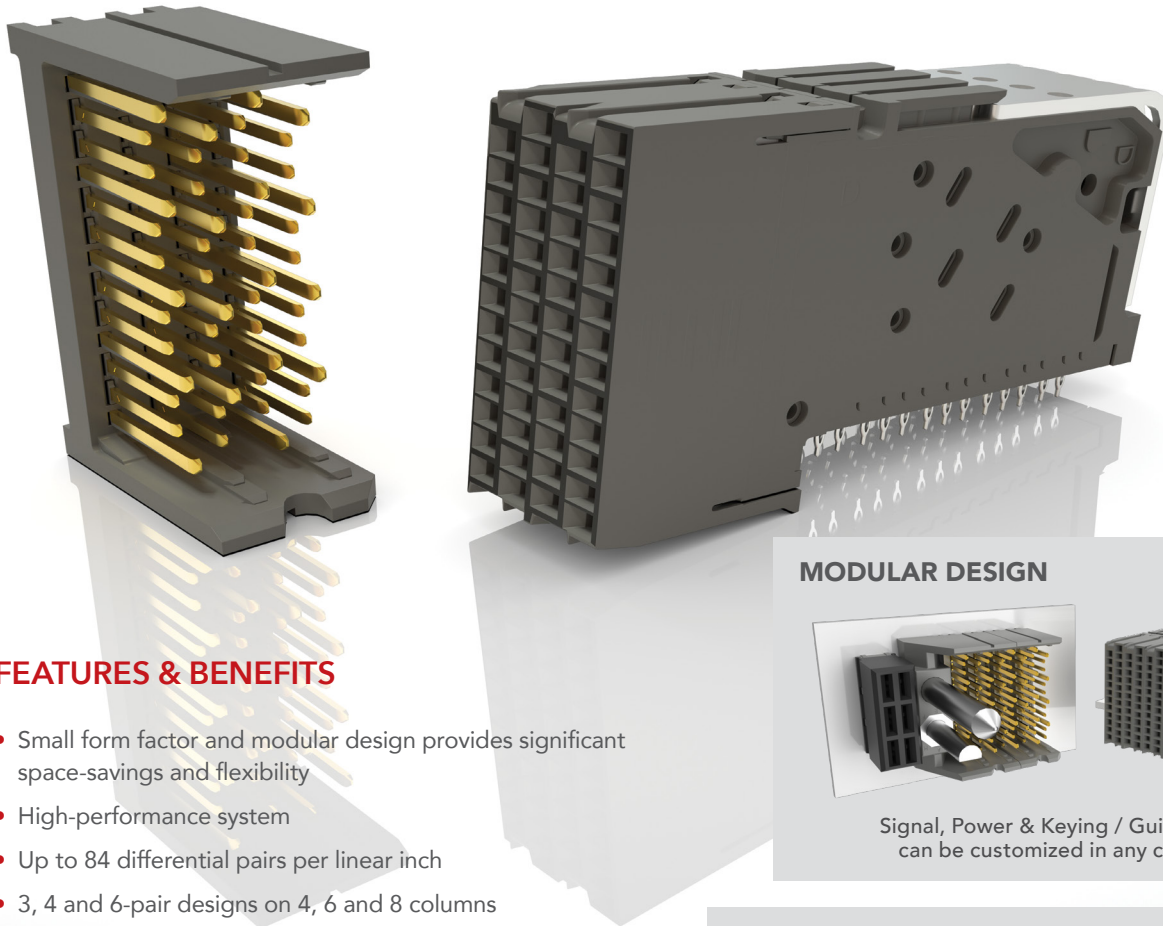
# HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

(1.80 mm) .071" PITCH

16 Gbps

FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility

- High-performance system

- Up to 84 differential pairs per linear inch

- 3, 4 and 6-pair designs on 4, 6 and 8 columns

- Integrated power, guidance, keying and side walls available

- 85 Ω and 100 Ω options

- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane. Visit **samtec.com?BSP** or contact **HSBP@samtec.com**

- Press-fit extraction and insertion tool options; please visit **samtec.com/tooling** for details

MODULAR DESIGN
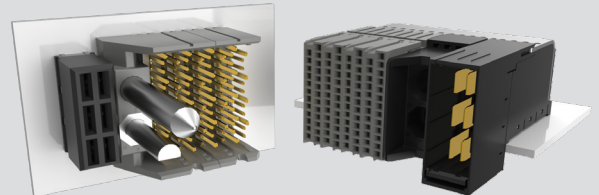
Signal, Power & Keying / Guidance options can be customized in any configuration

HIGH-DENSITY, SMALL FORM FACTOR
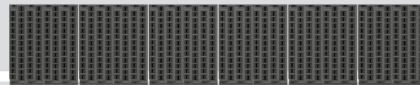
XCede® HD
Up to 84 pairs per linear inch

Traditional Backplane
Up to 76 pairs per linear inch

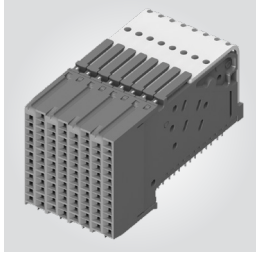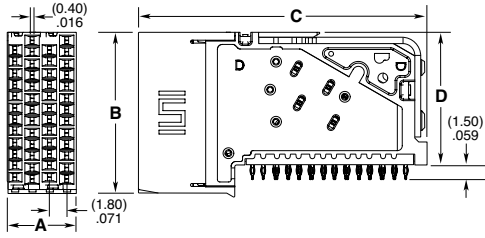(Both shown with six 4-pair, 8 column receptacles)

KEY SPECIFICATIONS

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING
HDTM/HDTF	LCP	Phosphor Bronze (HDTM) Copper Alloy (HDTF)	Au or Sn over 50 μ" (1.27 μm) Ni	-40 ˚C to + 105 ˚C	1.5 A per contact	48 VAC/ /68 VDC
HPTS/HPTT	LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-40 ˚C to + 105 ˚C	10 A per blade	48 VAC/ /68 VDC

XCede® HD

HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	–3, –4, –6	–04, –06, –08	**–S** = 30 µ" (0.76 µm) Gold on Contact Area, Matte Tin on Tail		**–LC** = Standard **–HS** = High-Speed	**–100** = 100 Ω **–085** = 85 Ω

HDTF
Board Mates:
HDTM

(0.40) .016
C
B
D
D
(1.50) .059
A
(1.80) .071
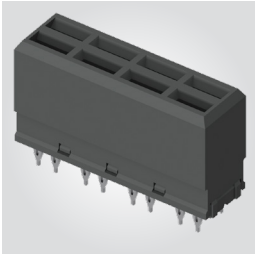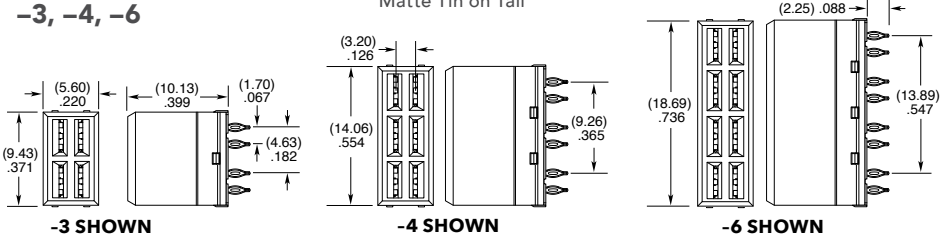
NO. OF COLUMNS	A
–04	(7.2) .283
–06	(10.8) .425
–08	(14.4) .567

PAIRS PER COLUMN	B	C	D
–3	(12.8) .504	(26.0) 1.02	(9.9) .390
–4	(16.4) .646	(29.4) 1.16	(13.5) .531
–6	(23.6) .929	(36.6) 1.44	(20.7) .815

View complete specifications at: **samtec.com?HDTF**

HPTS	BODY HEIGHT	PLATING	D	ORIENTATION
= Socket	Based on Pair Count of Signal Modules (HDTM) **–3, –4, –6**	**–S** = Standard Gold on Contact Area, Matte Tin on Tail		**–VT** = Vertical

HPTS
Mates with:
HPTT, BSP

(5.60) .220
(10.13) .399
(1.70) .067
(9.43) .371
(4.63) .182
–3 SHOWN

(3.20) .126
(14.06) .554
(9.26) .365
–4 SHOWN

(2.25) .088
(18.69) .736
(13.89) .547
–6 SHOWN
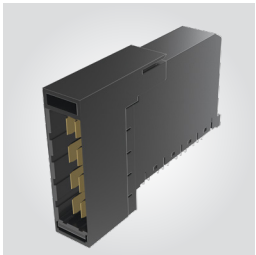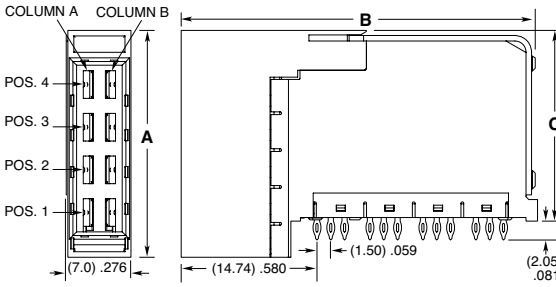
View complete specifications at: **samtec.com?HPTS**

HPTT	BODY HEIGHT	PLATING	POSITION NO. 1	POSITION NO. 2	POSITION NO. 3	POSITION NO. 4	D	ORIENTATION
= Terminal	Based on Pair Count of Signal Modules (HDTF, BSP) **–3, –4, –6**	**–S** = Standard Gold on Contact Area, Matte Tin on Tail	Contact Wipe Column A & B **–3** = (4.5 mm) 0.18" **–6** = (5.5 mm) 0.22"	Contact Wipe Column A & B **–3** = (4.5 mm) 0.18" **–6** = (5.5 mm) 0.22"	Contact Wipe Column A & B (–4 & –6 Height Only) **–3** = (4.5 mm) 0.18" **–6** = (5.5 mm) 0.22"	Contact Wipe Column A & B (–6 Height Only) **–3** = (4.5 mm) 0.18" **–6** = (5.5 mm) 0.22"		**–RA** = Right-angle

HPTT
Mates With:
HPTS

BODY HEIGHT	A	B	C
–3	(13.8) .543	(28.1) 1.11	(9.80) .386
–4	(17.4) .685	(31.2) 1.23	(13.50) .531
–6	(24.6) .969	(38.7) 1.52	(20.70) .815

COLUMN A   COLUMN B
POS. 4
POS. 3
POS. 2
POS. 1
A
(7.0) .276
B
C
(14.74) .580
(1.50) .059
(2.05) .081
–6 SHOWN

Notes:
Some lengths, styles and options are non-standard, non-returnable. XCede® is a registered trademark of Amphenol.

View complete specifications at: **samtec.com?HPTT**

Mouser Electronics

Authorized Distributor

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[Samtec](#):

HDTF-4-04-S-RA-LC-100 HDTF-4-06-S-RA-LC-100 HDTF-4-08-S-RA-LC-100 HDTF-4-04-S-RA-HS-100 HDTF-4-06-S-RA-HS-100 HDTF-4-08-S-RA-HS-100 HDTF-6-04-S-RA-LC-100 HDTF-6-06-S-RA-HS-100 HDTF-6-06-S-RA-LC-100 HDTF-6-08-S-RA-HS-100 HDTF-6-08-S-RA-LC-100 HDTF-4-08-S-RA-HS-085 HDTF-4-06-S-RA-LC-085 BSP-226769-01 HDTF-4-08-S-RA-LC-085 HDTF-6-08-S-RA-LC-085 HDTF-6-06-S-RA-HS-085